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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Ozis et al.

Application No. 10/683,575

Filed: October 9, 2003

Confirmation No. 9457

For: MODELING SUBSTRATE NOISE
COUPLING USING SCALABLE
PARAMETERS

Examiner: --

Art Unit: 2123

Attorney Reference No. 245-66956-01

CERTIFICATE OF MAILING

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Attorney
for Applicants

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9/3/04

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Listed on the accompanying form PTO-1449 and enclosed herewith are several English-language documents. Applicants respectfully request that these documents be listed as references cited on the issued patent.

If the present application was filed after June 30, 2003, copies of United States patents and United States published patent applications do not have to be provided to the Patent Office. This requirement of 37 C.F.R. § 1.98(a)(2)(i) has been waived by the United States Patent and Trademark Office pursuant to the Official Gazette Notice on August 5, 2003 (1276 OG 55). Applicants will provide copies of such patents upon request.

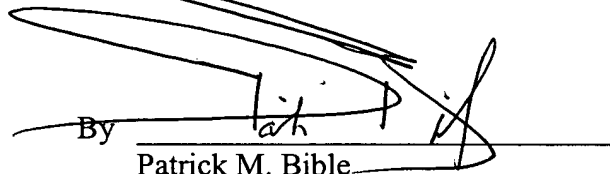
Applicants filed this Information Disclosure Statement ("IDS") before the mailing date of a first Office action on the merits. As a result, no fee should be required to file this IDS.

However, if the Patent Office determines that a fee is required for Applicants to file this IDS, please charge any such fees, or credit overpayment, to Deposit Account No. 02-4550. A **duplicate** copy of this Information Disclosure Statement is enclosed.

The filing of this IDS shall not be construed to be an admission that the information cited in the statement is, or is considered to be, prior art or otherwise material to patentability as defined in 37 C.F.R. §1.56.

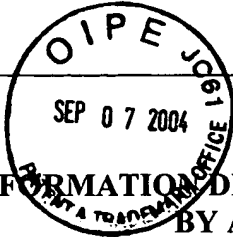
Respectfully submitted,

KLARQUIST SPARKMAN, LLP


By _____
Patrick M. Bible
Registration No. 44,423

One World Trade Center, Suite 1600
121 S.W. Salmon Street
Portland, Oregon 97204
Telephone: (503) 226-7391
Facsimile: (503) 228-9446

cc: Client
Docketing



INFORMATION DISCLOSURE STATEMENT BY APPLICANT

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First Named Inventor	Ozis
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Examiner's Initials*	Cite No. (optional)	OTHER DOCUMENTS
		Blalack et al., "Experimental Results and Modeling of Noise Coupling in a Lightly Doped Substrate," <i>IEEE IEDM 96</i> , pp. 623-626 (1996).
		Blalack, "Switching Noise in Mixed-Signal Integrated Circuits," Department of Electrical Engineering, Stanford University, 3 pp. from http://cis.stanford.edu/icl/wooley-grp/tallis/tallis.html (accessed on February 18, 2004).
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EXAMINER
SIGNATURE:

DATE
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* Examiner: Initial if reference considered, whether or not in conformance with MPEP 609. Draw line through cite if not in conformance and not considered. Include copy of this form with next communication to applicant.

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		First Named Inventor	Ozis
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Examiner's Initials*	Cite No. (optional)	OTHER DOCUMENTS	
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